



## Materials Declaration Form

<b>IPC</b>	1752	<b>Version</b>	2
<b>Form Type *</b>	Distribute		
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
		<i>* : Required Field</i>	

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	2018-06-15
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**


<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ESDALC6V1P5	CJ0I*CLC6V15	A	Z55A	2018-06-15
	Amount	UoM	Unit type	ST ECOPACK Grade
	3.53	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SOT-665	1.7 - 1.5 - 0.525	5	gull wing	
Comment	Package: SOT 665			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption id.	Description

QueryList : ELV directive : 2000/53/EC amended 2016/774_May 2016	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
Exemption id.	Description

QueryList : California Prop65 list, dated 15th December 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			TRUE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			FALSE
Substance	amount in product (mg)	Application	ppm in product

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	CJ01*CLCGV15					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	0.211	mg	supplier	die	Silicon (Si)	7440-21-3		0.205	mg	971564	58074
				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	18957	1133
				supplier	Passivation	Silicon Oxide	7631-86-9		0.002	mg	9479	567
Leadframe	Copper and its alloy	1.592	mg	Supplier	alloy	Copper (Cu)	7440-50-8		1.535	mg	964196	434844
				Supplier	alloy	Iron (Fe)	7439-89-6		0.038	mg	23869	10765
				Supplier	alloy	Phosphorus (P)	7723-14-0		0.001	mg	629	282
				Supplier	alloy	Zinc (Zn)	7440-66-6		0.002	mg	1256	567
				Supplier	metallization	Silver (Ag)	7440-22-4		0.016	mg	10050	4533
Die attach	Other inorganic materials	0.030	mg	Supplier	glue	Aluminum oxide	1344-28-1		0.010	mg	333333	2833
				Supplier	glue	Diethylene glycol monoethyl ether acetate	112-15-2		0.010	mg	333333	2833
				Supplier	glue	Epoxy resins	25068-38-6		0.010	mg	333333	2833
Bonding wire	Other inorganic materials	0.014	mg	Supplier	wire	Copper (Cu)	7440-50-8		0.014	mg	1000000	3966
Encapsulation	Other organic materials	1.622	mg	Supplier	mold compound	Silica(Amorphous)	60676-86-0		1.379	mg	850185	390652
				Supplier	mold compound	Phenol Resin	29690-82-2		0.049	mg	30210	13881
				Supplier	mold compound	Epoxy Resin	25068-38-6		0.113	mg	69667	32011
				Supplier	mold compound	Metal Hydroxide	21645-51-2		0.041	mg	25277	11615
				Supplier	mold compound	Organosilicon Compound	proprietary		0.032	mg	19729	9065
Connection coating	Other inorganic materials	0.061	mg	Supplier	mold compound	Carbon Black	1333-86-4		0.008	mg	4932	2266
				Supplier	solder alloy	Sn	7440-31-5		0.061	mg	1000000	17280